

KB-5150/KB-5150A/5150& (ANSI : CEM-1)

覆铜箔改性环氧纸芯玻璃布复合基层压板

特点

- 优良的冲孔性，最佳冲孔温度为 45℃~70℃
- 良好的耐热性和耐湿性
- 符合 IPC-4101D/10 的规范要求
- 不推荐作 PTH 制程

Features

- Excellent punching property, Suitable for punching at 45℃~70℃
- Excellent heat resistance
- IPC-4101 D/10 specification is applicable
- Plated through holes are not recommended for the cellulose core is easily attacked by the Electrolyte

注：耐漏电起痕指数 KB-5150 CTI≥175V KB-5150A CTI≥300V KB-5150& CTI≥600V

General Properties 一般特性

| Test Item 测试项目 | Unit 单位 | Test Method (IPC-TM-650) 测试方法 | Test Condition 处理条件 | Specification (IPC-4101D) 规格值 | Typical Value 典型值 |
|--|-------------------|-------------------------------------|--------------------------------|-------------------------------------|----------------------|
| Peel Strength (1 oz.) 铜箔剥离强度 | N/mm | 2.4.8 | 125℃ | -- | 1.65 |
| | | | Float 260℃ / 10 Sec | ≥1.05 | 1.6/1.45 |
| Thermal Stress 热应力 | Sec | 2.4.13.1 | Float 260℃/unetched | ≥10 | 25 |
| Bow / Twist 弯弓度/翘曲度 | % | 2.4.22.1 | A | ≤ 1.5 | 0.3 / 0.4 |
| Flexural Strength 抗弯强度 | N/mm ² | 2.4.4 | Length direction | ≥242 | 420 |
| | | | Cross direction | ≥172 | 290 |
| Flammability 燃烧性 | Rating | UL94 | UL-94 | UL94 V-0 | V-0 |
| Surface Resistivity 表面电阻 | MΩ | 2.5.17.1 | C-96/35/90 | ≥1.0×10 ⁴ | 1.0×10 ⁷ |
| Volume Resistivity 体积电阻 | MΩ-cm | 2.5.17.1 | C-96/35/90 | ≥1.0×10 ⁶ | 1.0×10 ⁸ |
| Z-Axis Expansion Z轴热膨胀系数 | ppm/℃ | 2.4.24 | E-2/105 TMA | --- | 100/320 |
| | % | | | --- | 6.0 |
| Dielectric Constant 介电常数 | — | 2.5.5.2 | Etched/@1 MHZ | ≤5.4 | 4.6 |
| Loss Tangent 介质损耗 | — | 2.5.5.2 | Etched/@1 MHZ | ≤0.035 | 0.023 |
| Arc Resistance 耐电弧性 | Sec | 2.5.1 | D-48/50+D-0.5/23 | ≥60 | 125 |
| Moisture Absorption 吸水率 | % | 2.6.2.1 | D-24/23 | ≤0.5 | 0.15 |
| Comparative Tracking Index 相比漏电起痕指数 | V | IEC 60112 | Etched/0.1% NH ₄ CL | ≥175 | 175/300/600 |

Remarks: Specimen Thickness: 1.6mm 1/0 样品厚度: 1.6mm 1/0

A = Keep the specimen originally without any process 保持原样, 不作处理

C = Temperature and humidity conditioning 在恒温恒湿的空气中处理

D = Immersing in distilled water with temperature control 浸在恒温的水中处理

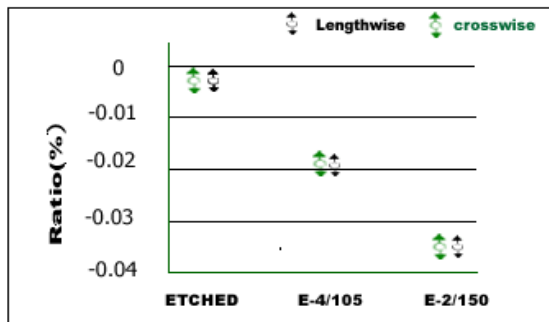
E = Temperature conditioning 在恒温的空气中处理

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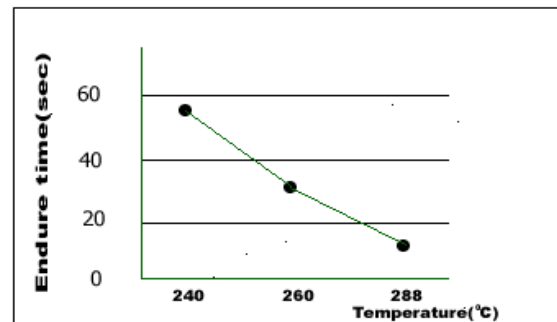
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Speciality Chart 板材特性图

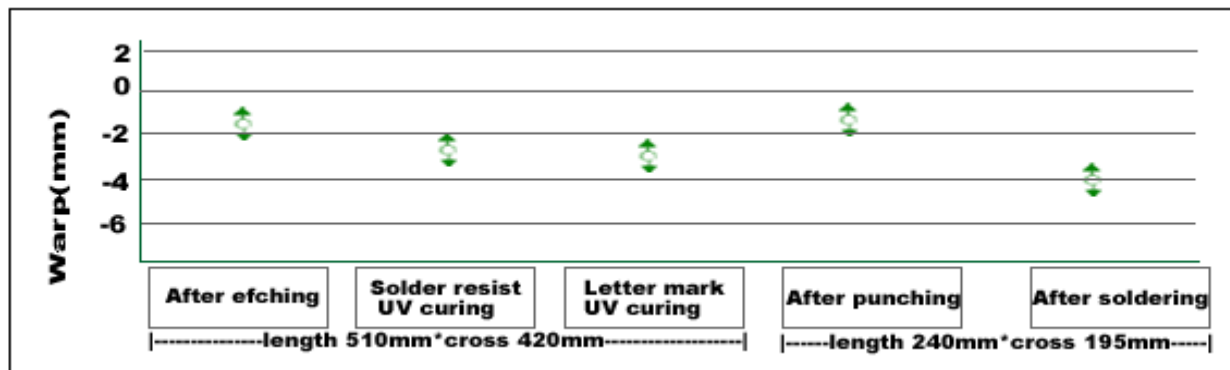
Dimensional stability 尺寸稳定性



Solder Resistance 耐焊性



Warpage through PCB process (thickness 1.6mm single side)



应用领域

- 显示器、录像机、电源基板、工业仪表、数码刻录机等

Applications

- Display, VCR, Power supply, Industrial Instrument, Digital sound recorder, etc.

Purchasing Information 采购信息

| Base Color 基材颜色 | Thickness 厚度 | Copper Cladding 铜箔厚度 | Regular Size (mm) 常规尺寸 | CTI Value CTI 值 |
|----------------------|-----------------|-------------------------|---------------------------|--------------------|
| CEM-1(纯白 pure-white) | 0.8mm~ 1.6mm | 18μm | 915*1220mm (36"*48") | KB-5150:175V |
| CEM-1W(白色 white) | | 35μm | 1020*1220mm (40"*48") | KB-5150A:300V |
| CEM-1F(黄色 yellow) | | 70μm | 1067*1220mm (42"*48") | KB-5150&: 600V |

Note: Other sheet size and thickness could be available upon request.

可根据客户要求提供其它尺寸和厚度

KB-5150& Not recommended for solder mask rework

KB-5150&不适合翻洗绿油(阻焊油墨)